SMD Power Inductor

TMPC1004H-Series(G)-D

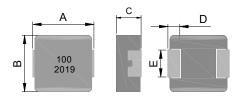
1. Features

- 1. Carbonyl Powder.
- 2. Compact design.
- 3. High current , low DCR , high efficiency.
- 4. Very low acoustic noise and very low leakage flux noise.
- 5. High reliability.
- 6. 100% Lead(Pb)-Free and RoHS compliant.
- 7. Operating temperature -40~+125 $^{\circ}$ C(Including self temperature rise)

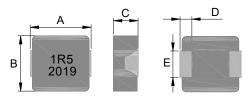
2. Applications

Note PC power system $\,^{,}$ incl. IMVP-6 DC/DC converter .

3. Dimensions



leadframe

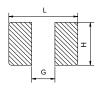


non-leadframe

Series	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	
TMPC1004H	11.0±0.5	10.0±0.3	3.8±0.2	2.3±0.3	3.0±0.3	



Recommend PC Board Pattern



L(mm)	G(mm)	H(mm)		
13.6	5.4	3.5		

Note: 1. The above PCB layout reference only.
2. Recommend solder paste thickness at
0.15mm and above.

4. Part Numbering

TMPC	1004	H	-	100	MG -	D
Α	В	С		D	F	F

A: Series

B: Dimension

C: Type

D: Inductance

E: Inductance Tolerance

F: Code

BxC

Carbonyl Powder.

100=10.0uH

 $K=\pm 10\%$, $L=\pm 15\%$, $M=\pm 20\%$, $N=\pm 25\%$, $Y=\pm 30\%$.

Marking: Black100 and 2019(20YY,19 WW,follow production date).

TAI-TECH P2

5. Specification

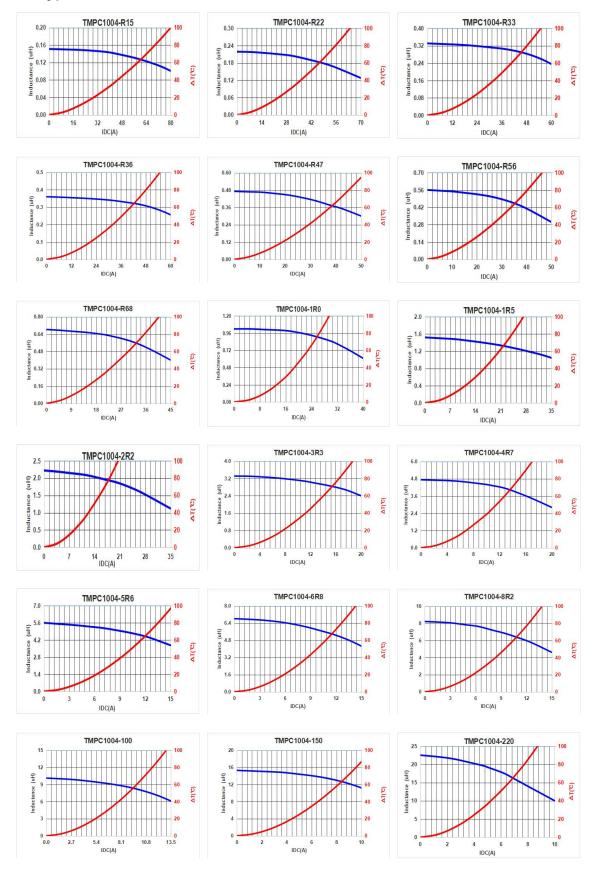
Part Number	Inductance L0 (uH)±20%	I rms (A)	I sat (A)	DCR(mΩ) Typ.@25℃	DCR(mΩ) Max.@25℃	Туре	
TMPC1004H-R15YG-D	0.15±30%	43.0	75.0	0.50	0.60	non-leadframe	
TMPC1004H-R22MG-D	0.22	35.0	60.0	0.80	1.00	non-leadframe	
TMPC1004H-R33MG-D	0.33	31.0	60.0	1.00	1.20	non-leadframe	
TMPC1004H-R36MG-D	0.36	31.0	60.0	1.05	1.20	non-leadframe	
TMPC1004H-R47MG-D	0.47	28.0	43.0	1.30	1.50	non-leadframe	
TMPC1004H-R56MG-D	0.56	25.0	40.0	1.60	1.80	non-leadframe	
TMPC1004H-R68MG-D	0.68	22.0	39.0	2.40	2.70	non-leadframe	
TMPC1004H-1R0MG-D	1.00	18.0	36.0	3.00	3.30	non-leadframe	
TMPC1004H-1R5MG-D	1.50	16.0	33.0	4.00	4.60	non-leadframe	
TMPC1004H-2R2MG-D	2.20	12.0	27.0	6.50	7.00	leadframe	
TMPC1004H-3R3MG-D	3.30	11.0	20.0	10.8	11.8	leadframe	
TMPC1004H-4R7MG-D	4.70	10.0	17.0	15.0	15.5	leadframe	
TMPC1004H-5R6MG-D	5.60	9.00	14.0	17.0	19.3	Leadframe	
TMPC1004H-6R8MG-D	6.80	8.50	13.5	17.5	23.3	leadframe	
TMPC1004H-8R2MG-D	8.20	8.00	12.5	20.0	22.5	leadframe	
TMPC1004H-100MG-D	10.0	7.50	12.0	27.0	30.0	leadframe	
TMPC1004H-150MG-D	15.0	6.25	10.0	40.0	45.0	leadframe	
TMPC1004H-220MG-D	22.0	5.00	7.00	64.0	74.0	leadframe	
TMPC1004H-330MG-D	33.0	3.50	5.00	92.0	112	leadframe	
TMPC1004H-470MG-D	47.0	3.00	4.50	145	167	leadframe	

Note:

- 1. Test frequency: Ls: 100KHz /1.0V.
- 3. Testing Instrument(or equ): L: HP4284A,CH11025,CH3302,CH1320,CH1320S LCR METER / Rdc:CH16502,Agilent33420A MICRO OHMMETER.
- 4. Heat Rated Current (Irms) will cause the coil temperature rise approximately $\,\Delta \, T$ of 40 $^{\circ} \! C$
- 5. Saturation Current (Isat) will cause L0 to drop approximately 30%.
- 6. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions. Circuit design, component, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
- 7. Special inquiries besides the above common used types can be met on your requirement.

TAI-TECH P3

6. Typical Performance Curves



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